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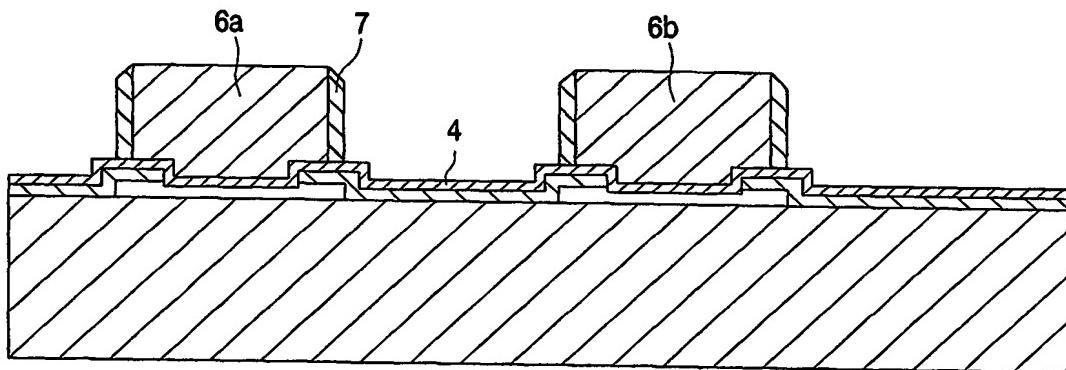
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(54) Title: METAL BUMP WITH AN INSULATION FOR THE SIDE WALLS AND METHOD OF FABRICATING A CHIP WITH SUCH A METAL BUMP



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(57) Abstract: A chip with at least two metal bumps (6a, 6b) which has insulation layers for opposing side walls which are deposited in a plasma activated gas. Predetermined portions of the insulation layer (7) are removed by reactive ion etching. The metal bumps can be formed of a noble metal and the insulation layer of a dielectric material such as SiO₂ Si₃N₄.